

RELIABILITY MONITOR

PROCESS: 2P, 2M, 0.6um, P2Cap, PdD, HP Vts, GOI, WJ BPSG, N+ESDII,

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS21352	A4	AUG '02	30219	0240	Stats	DC039494AA	LQFP	500	77	0
DS21352	A4	AUG '02	30219	0240	Stats	DC039494AA	LQFP	1000	77	0

TOTALS:

FAIL RATE (Fits): 13 DEVICE HRS: 7.26E+07 0

RELIABILITY MONITOR

PROCESS: D8R-2P2M,HPVt,NDROM,N+ESD,Laser N-sub,LOCOS:GOI

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS2154	A2	NOV '02	30236	0230	Stats	DC102671AA	LQFP	500	80	2

TOTALS:

FAIL RATE (Fits): 83 DEVICE HRS: 3.73E+07 2

RELIABILITY MONITOR

PROCESS: D6W-1P2M,HPVt,E2,TCZ PBL:GOI

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS1100	A3	OCT '01	28535	0126	ATP (Amkor, PI)	DK114601AD	SOIC	336	77	0
DS1100	A3	JAN '02	28614	0132	ATP (Amkor, PI)	DK115002AK	SOIC	336	77	0
DS1100	A3	OCT '01	28535	0126	ATP (Amkor, PI)	DK114601AD	SOIC	1000	77	0
DS1100	A3	JAN '02	28614	0132	ATP (Amkor, PI)	DK115002AK	SOIC	1000	77	0

TOTALS:

FAIL RATE (Fits): 6 DEVICE HRS: 1.45E+08 0

RELIABILITY MONITOR

PROCESS: 1P, 2M, 0.8um, ESD Pdepletion,HP Vts,WJ BPSG,Ti/TiN M1+M2,

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS1302	A4	SEP '02	30178	0226	CPS (ChipPac, China)	DE244426AA	PDIP	500	80	0
DS1302	A4	SEP '02	30178	0226	CPS (ChipPac, China)	DE244426AA	PDIP	1000	80	0

TOTALS: FAIL RATE (Fits): 12 DEVICE HRS: 7.55E+07 0

RELIABILITY MONITOR

PROCESS: D6RL-1P1M,SILP1,LLVt,N+ESD PBL:GOI

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS80C320	C5	DEC '02	30259	0230	ATP (Amkor, PI)	DK240563AB	PDIP	500	77	0
DS80C320	C5	DEC '02	30259	0230	ATP (Amkor, PI)	DK240563AB	PDIP	1000	77	0

TOTALS:

FAIL RATE (Fits): 13 DEVICE HRS: 7.26E+07 0

RELIABILITY MONITOR

PROCESS: 1P, 1M, 0.6um, Pd, Ti/TiN M1 , WJ BPSG ,

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS2401	C2	AUG '02	30203	0245	Hana	DU218017AG	TO92	500	80	0
DS2401	C2	AUG '02	30203	0245	Hana	DU218017AG	TO92	1000	80	0

TOTALS: FAIL RATE (Fits): 12 DEVICE HRS: 7.55E+07 0

RELIABILITY MONITOR

PROCESS: D8W-1P1M,HPVt,E2 LOCOS:GOI

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS1620	D1	JUL '02	30102	0114	CPS (ChipPac, China)	DH052446AAF	SOIC	500	79	0
DS1620	D1	JUL '02	30102	0114	CPS (ChipPac, China)	DH052446AAF	SOIC	1000	79	0
DS1621	A7	SEP '02	30117	0232	ATP (Amkor, PI)	DK103506AA	SOIC	500	77	0
DS1621	A7	SEP '02	30117	0232	ATP (Amkor, PI)	DK103506AA	SOIC	1000	77	0

TOTALS:

FAIL RATE (Fits): 6 DEVICE HRS: 1.47E+08 0

RELIABILITY MONITOR

PROCESS: 1P, 1M, 1.2um, II Poly1 , TEOS Spacer,

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS1267	A1	AUG '02	30199	0237	Carsem	DM234023AF	TSSOP	500	79	0

TOTALS: FAIL RATE (Fits): 25 DEVICE HRS: 3.73E+07 0